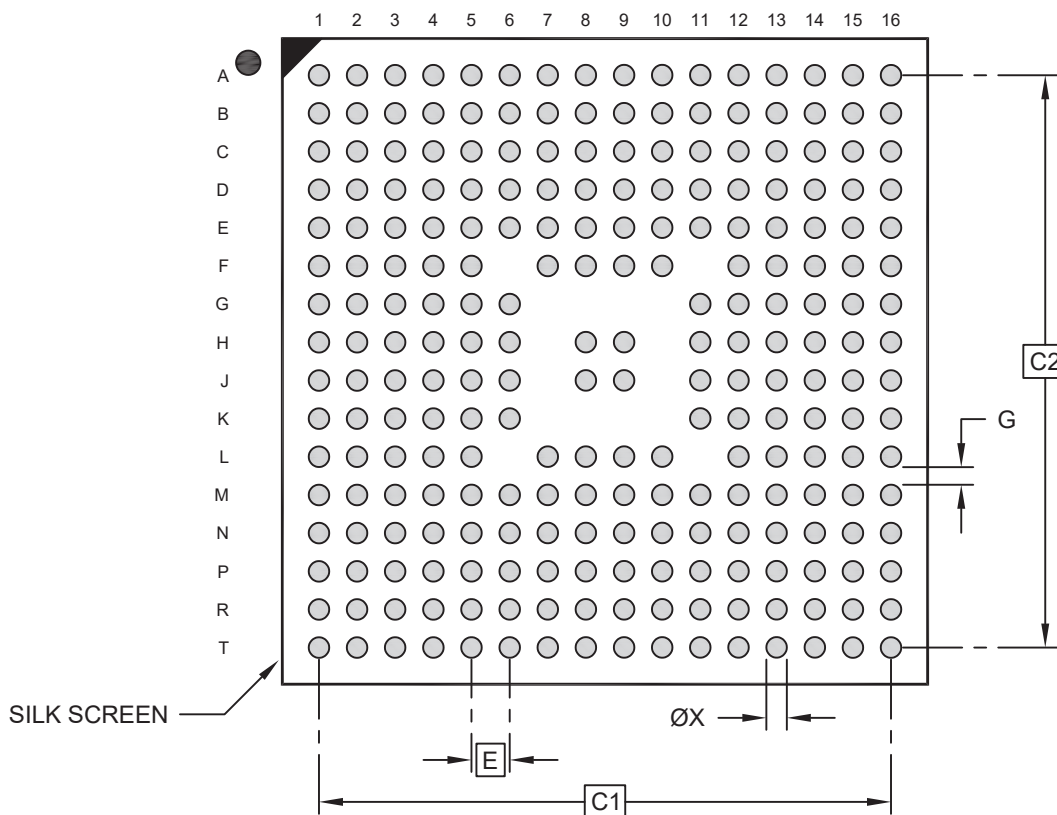


240-Ball Thin Fine-Pitch Ball Grid Array (4PB) - 11x11x1.217 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Contact Pad Spacing	C1		9.75 BSC	
Contact Pad Spacing	C2		9.75 BSC	
Contact Pad Diameter	X			0.35
Contact Pad to Contact Pad	G	0.30		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.